Title (en)

MULTI-LAYER CIRCUIT CARRIER AND PRODUCTION THEREOF

Title (de)

MEHRLAGIGER SCHALTUNGSTRÄGER UND HERSTELLUNG DESSELBEN

Title (fr)

SUPPORT DE CIRCUIT A PLUSIEURS COUCHES ET FABRICATION DUDIT SUPPORT

Publication

EP 1532681 A1 20050525 (DE)

Application

EP 03783945 A 20030731

Priority

- DE 0302575 W 20030731
- DE 10235332 A 20020801

Abstract (en)

[origin: DE10235332A1] Multiple layer switch support (1) comprises a semiconductor chip (2) and/or a discrete component (3), a rewiring layer (5) having a rewiring structure (4), an insulating layer (7) with through-structures (6), and outer contact surfaces (8) arranged on the lower side (9) of the switch support as outer contact layer. Multiple layer switch support (1) comprises a semiconductor chip (2) and/or a discrete component (3), a rewiring layer (5) having a rewiring structure (4), an insulating layer (7) with through-structures (6), and outer contact surfaces (8) arranged on the lower side (9) of the switch support as outer contact layer. An anchoring layer (12) is arranged between the rewiring layer and the insulating layer and contains metallic plates (13) for fixing the through-structures in the switch support. The outer contact surfaces and the metallic plates are electrically connected to the rewiring structure. Independent claims are also included for processes for the production of the switch support.

IPC 1-7

H01L 23/498; H01L 21/48; H01L 21/68

IPC 8 full level

H01L 21/48 (2006.01); **H01L 23/055** (2006.01); **H01L 23/31** (2006.01); **H01L 23/498** (2006.01); **H01L 23/538** (2006.01); **H05K 1/11** (2006.01); **H05K 3/46** (2006.01); H01L 27/146 (2006.01); H01L 31/0203 (2006.01); H05K 3/20 (2006.01)

CPC (source: EP US)

H01L 21/4857 (2013.01 - EP US); **H01L 21/486** (2013.01 - EP US); **H01L 23/055** (2013.01 - EP US); **H01L 23/3121** (2013.01 - EP US); **H01L 23/49805** (2013.01 - EP US); **H01L 23/49811** (2013.01 - EP US); **H01L 23/49822** (2013.01 - EP US); **H01L 23/49827** (2013.01 - EP US); **H01L 23/49833** (2013.01 - EP US); **H01L 23/49861** (2013.01 - EP US); **H01L 23/5389** (2013.01 - EP US); **H05K 1/113** (2013.01 - EP US); **H05K 3/4647** (2013.01 - EP US); **H05K 3/4682** (2013.01 - EP US); H01L 24/48 (2013.01 - EP US); H01L 24/73 (2013.01 - EP US); H01L 27/14618 (2013.01 - EP US); H01L 31/0203 (2013.01 - EP US); H01L 2224/05599 (2013.01 - EP US); H01L 2224/16225 (2013.01 - EP US); H01L 2224/32013 (2013.01 - EP US); H01L 2224/32225 (2013.01 - EP US); H01L 2224/45099 (2013.01 - EP US); H01L 2224/48091 (2013.01 - EP US); H01L 2224/48227 (2013.01 - EP US); H01L 2224/48465 (2013.01 - EP US); H01L 2224/73204 (2013.01 - EP US); H01L 2224/73265 (2013.01 - EP US); H01L 2224/85399 (2013.01 - EP US); H01L 2924/00014 (2013.01 - EP US); H01L 2924/01004 (2013.01 - EP US); H01L 2924/01013 (2013.01 - EP US); H01L 2924/01029 (2013.01 - EP US); H01L 2924/01068 (2013.01 - EP US); H01L 2924/01077 (2013.01 - EP US); H01L 2924/01079 (2013.01 - EP US); H01L 2924/01322 (2013.01 - EP US); H01L 2924/12041 (2013.01 - EP US); H01L 2924/14 (2013.01 - EP US); H01L 2924/15174 (2013.01 - EP US); H01L 2924/15184 (2013.01 - EP US); H01L 2924/15311 (2013.01 - EP US); H01L 2924/15313 (2013.01 - EP US); H01L 2924/16152 (2013.01 - EP US); H01L 2924/16195 (2013.01 - EP US); H01L 2924/181 (2013.01 - EP US); H01L 2924/30107 (2013.01 - EP US); H01L 2924/3025 (2013.01 - EP US); H05K 3/205 (2013.01 - EP US); H05K 2201/2072 (2013.01 - EP US); H05K 2203/0733 (2013.01 - EP US)

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